EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	10/582,711	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 02:15
L2	910	(substrate or wafer) with (backside or back) with (contact or metal or conductor or connect$3) with (trench or hole or via or open) with (polish$3 or thin $4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 03:25
L3	358	L2 and @pd<"20031212"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 03:25
L4	17618	(epi or epitax$3) with (trench or hole or via or open)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 03:26
L5	403	L4 with (conduct$3 or contact or connect$3) with (liner or barrier or fill)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 03:26
L6	209	L5 and (@pd<"20031212" or @ad<"20031212" or @rlad<"20031212")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 03:26
S1	12205	(epi or epitax$3) with layer with (trench or hole or via or open)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/03 12:11

S2	552	S1 with (diode or sensor or PD)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/03 12:12
S3	40	S2 with (conduct$3 or contact or connect$3) with (liner or barrier or fill)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/03 12:14
S4	53	S2 same (conduct$3 or contact or connect$3) with (liner or barrier or fill)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/03 12:19
S5	1178	S1 same (diode or sensor or PD)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/03 12:21
S6	131	S5 same (conduct$3 or contact or connect$3) same (liner or barrier or fill)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/03 12:21
S7	81	S6 and (@pd<"20031212" or @ad<"20031212" or @rlad<"20031212")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/03 12:23
S8	16746	(epi or epitax$3) with (trench or hole or via or open)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/03 12:48
S9	360	S8 with (conduct$3 or contact or connect$3) with (liner or barrier or fill)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/03 12:49
S10	209	S9 and (@pd<"20031212" or @ad<"20031212" or @rlad<"20031212")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/03 12:49

S11	4	("6960483" "7217590").pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/04 09:40
S12	11	("4477835" | "5144747" | "5244817" | "5250843" | "5274250" | "5568574" | "6091194" | "6252220" | "6257491" | "6646289").PN. OR ("6960483" | "7217590"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 09:40
S13	7	pourquier-eric.in.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 09:41
S14	43838	(substrate or wafer) with (backside or back) with (contact or metal or conductor or connect$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/11 05:16
S15	8788	(substrate or wafer) with (backside or back) with (contact or metal or conductor or connect$3) with (trench or hole or via or open)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/11 05:17
S16	863	(substrate or wafer) with (backside or back) with (contact or metal or conductor or connect$3) with (trench or hole or via or open) with (polish$3 or thin $4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/11 05:17
S17	358	S16 and @pd< "20031212"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/11 05:18
S18	0	wo03/019669	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/13 08:24

1/ 26/ 2010 3:27:05 AM
C:\ Documents and Settings\ ejones1\ My Documents\ EAST\ Workspaces
\ 10582711 AI MAGESENSOR.wsp